

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-10 (cancelled)

Claims 11-20 (cancelled)

Claim 21 (previously presented) A surface acoustic wave duplexer having an antenna terminal, a transmitting terminal and a receiving terminal, comprising:

 a transmitting SAW filter coupled between the antenna terminal and the transmitting terminal;

 a receiving SAW filter coupled between the antenna terminal and the receiving terminal;

 a common piezoelectric substrate on which both of the transmitting SAW filter and the receiving SAW filter are formed; and

 a package covering the common piezoelectric substrate, wherein the antenna terminal, the transmitting terminal and the receiving terminal are formed on the package; and

 a frequency adjusting circuit being coupled between the antenna terminal and the transmitting SAW filter or the receiving SAW filter, wherein the frequency adjusting circuit has a capacitance element.

Claim 22 (previously presented) A surface acoustic wave duplexer according to claim 21,
further comprising:

 a branching filter circuit coupled between the frequency adjusting circuit and the
transmitting SAW filter or the receiving SAW filter.

Claim 23 (currently amended) A surface acoustic wave duplexer according to claim ~~22~~23,
wherein the branching filter circuit is composed of a serial arm resonator.

Claim 24 (currently amended) A surface acoustic wave duplexer according to claim ~~23~~22,
wherein the branching filter circuit is formed on the common piezoelectric substrate with the
transmitting and receiving SAW filters.

Claim 25 (currently amended) A surface acoustic wave duplexer according to claim ~~23~~22,
wherein the package has a multi-layer structure.

Claim 26 (currently amended) A surface acoustic wave duplexer having an antenna
terminal, a transmitting terminal and a receiving terminal, comprising:

a transmitting SAW filter coupled between the antenna terminal and the transmitting
terminal;

a receiving SAW filter coupled between the antenna terminal and the receiving terminal;

a common piezoelectric substrate on which both of the transmitting SAW filter and the receiving SAW filter are formed; and

a package covering the common piezoelectric substrate, wherein the antenna terminal, the transmitting terminal and the receiving terminal are formed on the package;

a frequency adjusting circuit being coupled between the antenna terminal and the transmitting SAW filter or the receiving SAW filter, wherein the frequency adjusting circuit has a capacitance element~~according to claim 26;~~ and

a branching filter circuit coupled between the frequency adjusting circuit and the transmitting SAW filter or the receiving SAW filter, wherein the branching filter circuit is formed on the package.

Claim 27 (currently amended) A surface acoustic wave duplexer according to claim 26, wherein the ~~branching filter circuit is formed on the package~~package has a first layer substrate and a second layer substrate, the first layer substrate is disposed on the second layer substrate, and the branching filter circuit is formed on the first layer substrate or the second layer substrate of the package.

Claim 28 (cancelled)

Claim 29 (currently amended) A surface acoustic wave duplexer according to claim

[[1]]26, wherein the frequency adjusting circuit has an inductance element and a capacitance element.

Claim 30 (previously presented) A surface acoustic wave duplexer according to claim 27, wherein the frequency adjusting circuit is formed on the common piezoelectric substrate together with the branching filter circuit.

Claim 31 (cancelled)

Claim 32 (currently amended) A surface acoustic wave duplexer according to claim [[1]]26, wherein the frequency adjusting circuit is formed on the package.

Claim 33 (previously presented) A surface acoustic wave duplexer according to claim 21, wherein the package has a first layer substrate and a second layer substrate, the first layer substrate is disposed on the second layer substrate and the frequency adjusting circuit is formed on the first layer substrate or the second layer substrate.

Claim 34 (previously presented) A surface acoustic wave duplexer having an antenna terminal, a transmitting terminal and a receiving terminal, comprising:

 a SAW filter chip including a transmitting SAW filter connected with the transmitting

terminal and a receiving SAW filter connected with the receiving terminal, wherein both the transmitting SAW filter and the receiving SAW filter are formed on one common piezoelectric substrate;

a package covering the one common piezoelectric substrate, wherein the antenna terminal, the transmitting terminal and the receiving terminal are formed on the package; and

a frequency adjusting circuit being coupled between the antenna terminal and the transmitting SAW filter or the receiving SAW filter, wherein the frequency adjusting circuit has a capacitance element.

Claim 35 (previously presented) A surface acoustic wave duplexer according to claim 34, further comprising:

a branching filter circuit being coupled between the frequency adjusting circuit and the transmitting SAW filter or the receiving SAW filter.

Claim 36 (currently amended) A surface acoustic wave duplexer according to claim 35~~36~~, wherein the branching filter circuit is composed of a serial arm resonator.

Claim 37 (currently amended) A surface acoustic wave duplexer according to claim 35~~36~~, wherein the branching filter circuit is formed on the common piezoelectric substrate with the transmitting and receiving SAW filters.

Claim 38 (currently amended) A surface acoustic wave duplexer according to claim ~~34~~35, wherein the package has a multi-layer structure.

Claim 39 (currently amended) A surface acoustic wave duplexer having an antenna terminal, a transmitting terminal and a receiving terminal, comprising:

a SAW filter chip including a transmitting SAW filter connected with the transmitting terminal and a receiving SAW filter connected with the receiving terminal, wherein both the transmitting SAW filter and the receiving SAW filter are formed on one common piezoelectric substrate;

a package covering the one common piezoelectric substrate, wherein the antenna terminal, the transmitting terminal and the receiving terminal are formed on the package; and a frequency adjusting circuit being coupled between the antenna terminal and the transmitting SAW filter or the receiving SAW filter, wherein the frequency adjusting circuit has a capacitance element~~according to claim 35;~~ and

a branching filter circuit being coupled between the frequency adjusting circuit and the transmitting SAW filter or the receiving SAW filter, wherein the branching filter circuit is formed on the package.

Claim 40 (currently amended) A surface acoustic wave duplexer according to claim ~~35~~39,

wherein the package has a first layer substrate and a second layer substrate, the first layer substrate being disposed on the second layer substrate, and the branching filter circuit is formed on the first layer substrate or the second layer substrate.

Claim 41 (currently amended) A surface acoustic wave duplexer according to claim ~~36~~35,
~~further comprising:~~

wherein the frequency adjusting circuit ~~being~~is coupled between the antenna terminal and the branching filter circuit.

Claim 42 (previously presented) A surface acoustic wave duplexer according to claim ~~34~~39,
wherein the frequency adjusting circuit has an inductance element.

Claim 43 (previously presented) A surface acoustic wave duplexer according to claim 34,
wherein the frequency adjusting circuit is formed on the common piezoelectric substrate.

Claim 44 (previously presented) A surface acoustic wave duplexer according to claim 21,
wherein the package has a multi-layer structure.

Claim 45 (previously presented) A surface acoustic wave duplexer according to claim 34,
wherein the frequency adjusting circuit is formed on the package.

Claim 46 (previously presented) A surface acoustic wave duplexer according to claim 34, wherein the package has a first layer substrate and a second layer substrate, the first layer substrate being disposed on the second layer substrate, and the frequency adjusting circuit is formed on the first layer substrate or the second layer substrate.

Claim 47 (currently amended) A surface acoustic wave duplexer according to claim 26~~24~~, wherein capacitance element is coupled in series between the antenna terminal and the transmitting SAW filter or the receiving SAW filter.

Claim 48 (currently amended) A surface acoustic wave duplexer according to claim 39~~34~~, wherein the capacitance element is coupled in series between the antenna terminal and the transmitting SAW filter or the receiving SAW filter.

Claim 49 (new) A surface acoustic wave duplexer according to claim 26, wherein the branching filter circuit comprises a serial alarm resonator.

Claim 50 (new) A surface acoustic wave duplexer according to claim 39, wherein the branching filter circuit comprises a serial alarm resonator.